Rapid Manufacturing Technologies

Guest Editor:

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Message from the Guest Editor

Dear Colleagues,

The last three decades have seen the emergence and evolution of new manufacturing technologies that offer the benefits of complexity, speed, cost, and high quality of products. Rapid Manufacturing (RM) Technologies, based on Additive Manufacturing techniques (AM), make possible the fabrication of end-use items directly from Computer Aided Design (CAD) data. Despite significant research efforts, the evolution of RM technologies is far from complete with many significant challenges that need to be overcome. The aim of this Special Issue is to collect a series of articles (experimental, analytical and computational) related to technologies, methods, materials, systems and applications in the field of Rapid Manufacturing.

- Design optimization tools and strategies
- Simulation models for RM processes
- Process reliability and product quality
- Materials considerations and characterization
- Additive Manufacturing
- Application of available technologies
- 3D micro/nanostructures

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Special Issue

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Message from the Editor-in-Chief

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